

Electronic Patent Application Fee Transmittal

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|---|--|-----------------|---------------|---------------------------------|
| Application Number: | 09546174 | | | |
| Filing Date: | 11-Apr-2000 | | | |
| Title of Invention: | HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS | | | |
| First Named Inventor/Applicant Name: | Chih-Chien Liu | | | |
| Filer: | William H. Wright/Lillian Rodriguez | | | |
| Attorney Docket Number: | JIA 462C1 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 3 months with \$0 paid | 1253 | 1 | 1050 | 1050 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 1050 |